

SQA18N50

500V 18A N-channel Enhancement Mode Power MOSFET

Features

- Low on-Resistance: $R_{DS(on)}=0.203\ \Omega$ (typ.)
- Special Process Technology for high ESD Capability
- 100% Avalanche Test
- Good Stability and Uniformity with High E_{AS}

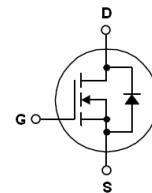
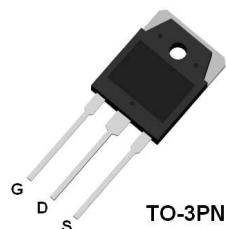
Description

The SQA18N50 is an N-Channel enhancement mode power MOSFET, it has low static on-resistance and high avalanche energy strength. This device provide excellent switching performance for UPS,DC-DC converters and AC-DC power supply.

Applications

- UPS Applications
- DC-DC Converters and AC-DC Power Supply

Package Type & Internal Circuit



Absolute Maximum Ratings @ $T_c=25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain to Source Voltage		500	V
V_{GSS}	Gate to Source Voltage		± 30	V
I_D	Drain Current	$T_c=25\text{ }^\circ\text{C}$	18	A
		$T_c=100\text{ }^\circ\text{C}$	10.8	A
I_{DM}	Pulsed Drain Current	(Note1)	92	A
P_D	Maximum Power Dissipation	$T_c=25\text{ }^\circ\text{C}$	235	W
	Derate above 25°C		1.88	W/ $^\circ\text{C}$
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	1298	mJ
T_J	Operating Junction Temperature Range		-55~+150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55~+150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{th(J-C)}$	Thermal Resistance, Junction to case	0.53	$^\circ\text{C}/\text{W}$
$R_{th(J-A)}$	Thermal Resistance, Junction to Ambient	60	$^\circ\text{C}/\text{W}$

Electrical Characteristics @ $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain to Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	500	-	-	V
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	3.0	4.1	5.0	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=9\text{A}$	-	0.223	0.260	Ω
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=V_{\text{DSS}}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate to Source Leakage Current	$V_{\text{GS}}=V_{\text{GSS}}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA

D-S Diode Characteristics and Maximum Rating @ $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Maximum Drain to Source Diode Forward Current		-	-	18	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_s=18\text{A}$	-	0.876	1.25	V
T_{rr}	Reverse Recovery Time	$V_{\text{GS}}=0\text{V}, I_s=18\text{A}, \frac{dI}{dt}=-100\text{A}/\text{us}$	-	0.55	-	us
Q_{rr}	Reverse Recovery Charge		-	5.5	-	μC

Switching Characteristics @ $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on Delay Time	$I_{\text{D}}=18\text{A}, V_{\text{DD}}=250\text{V}, R_{\text{G}}=25\Omega$ (Note 3)	-	70	-	ns
t_r	Turn-on Rise Time		-	190	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	100	-	ns
t_f	Turn-off Fall Time		-	100	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1.0\text{MHz}$	-	2500	-	pF
C_{oss}	Output Capacitance		-	400	-	pF
C_{rss}	Reverse Transfer Capacitance		-	40	-	pF
Q_g	Total Gate Charge	$I_{\text{D}}=18\text{A}, V_{\text{DS}}=400\text{V}$ (Note 3)	-	46	-	nC
Q_{gs}	Gate to Emitter Charge		-	14	-	nC
Q_{gd}	Gate to Collector Charge		-	22	-	nC

Note:

1. Repetitive rating: pulse-width limited by maximum junction temperature
2. $L=8.0\text{mH}, I_{\text{AS}}=18\text{A}, V_{\text{DD}}=50\text{V}, V_{\text{G}}=10\text{V}, @T_c=25^\circ\text{C}$
3. Essentially independent of operating temperature typical characteristics

Typical Performance Characteristics

Fig. 1. Typical on-Resistance Characteristics

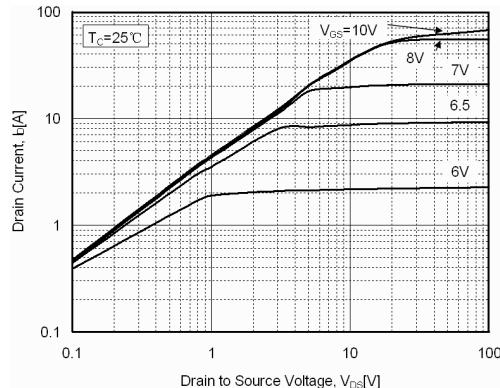
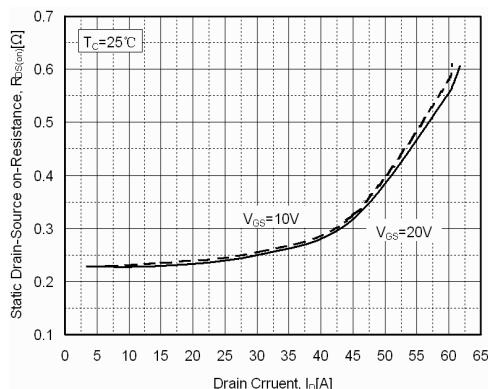
Fig. 3. Static on-Resistance vs. I_D 

Fig. 5. Capacitance Characteristics

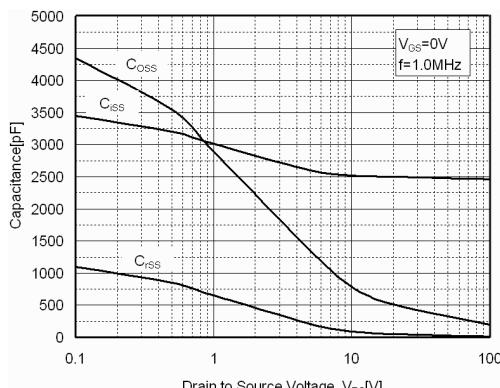


Fig. 2. Typical Transfer Characteristics

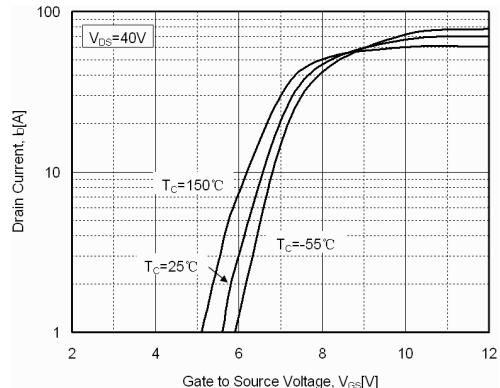
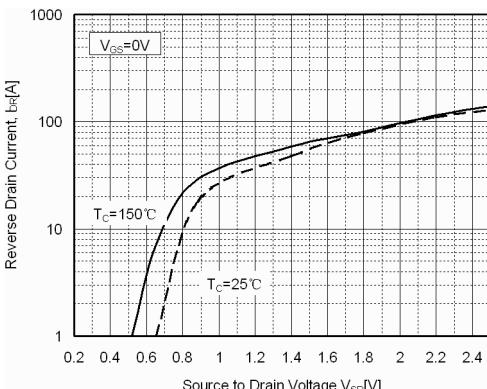
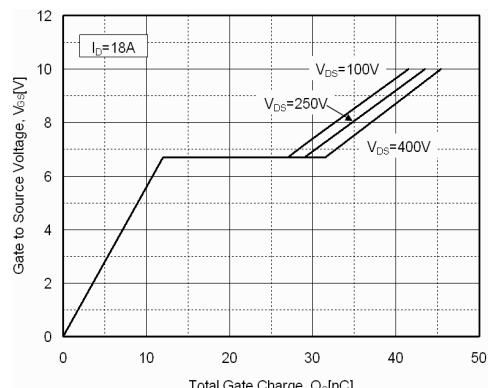
Fig. 4. Body Diode Forward Voltage vs. I_{DR} 

Fig. 6. Gate Charge Characteristics



Typical Performance Characteristics

Fig. 7. Breakdown Voltage vs. Temperature

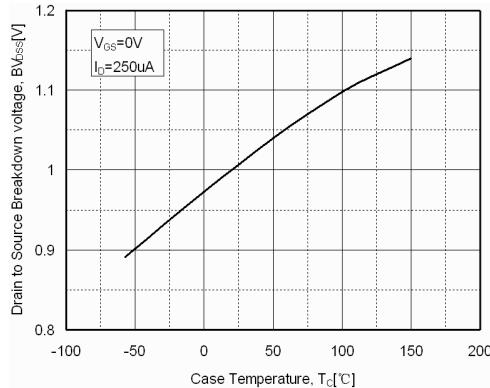


Fig. 8. Static on-Resistance vs. Temperature

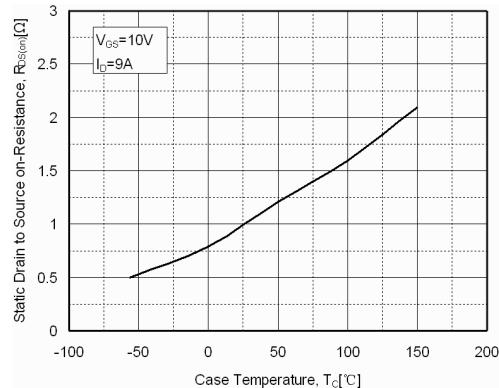


Fig. 9. Maximum Safe Operating Area

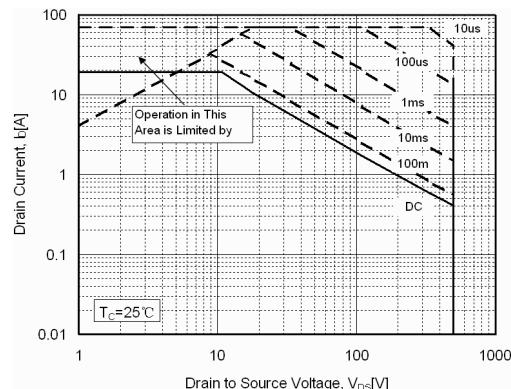


Fig. 10. Maximum Drain Current vs. Temperature

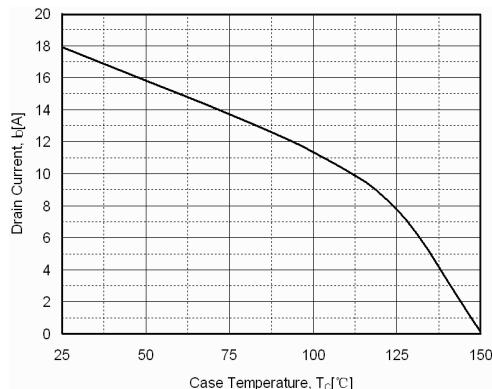
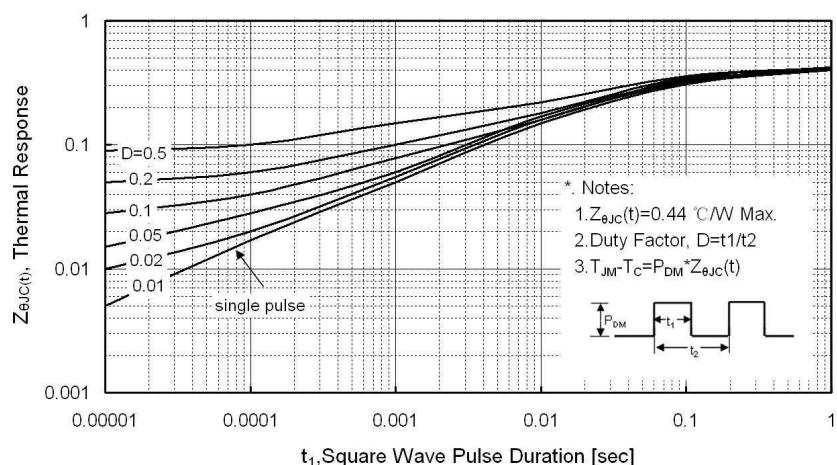


Fig. 11. Transient Thermal Response Curve



Package Dimensions

TO-3PN

(Dimensions in Millimeters)

